



3-wire Serial EEPROM 2K (256 x 8 or 128 x 16) and 4K (512 x 8 or 256 x 16)

DATASHEET

Features

- Low-voltage Operation
 - V_{CC} = 1.7V to 5.5V
- User-selectable Internal Organization
 - 2K: 256 x 8 or 128 x 16
 - 4K: 512 x 8 or 256 x 16
- 3-wire Serial Interface
- Sequential Read Operation
- 2MHz Clock Rate (5V)
- Self-timed Write Cycle (5ms Max)
- High Reliability
 - Endurance: 1,000,000 Write Cycles
 - Data Retention: 100 Years
- 8-lead JEDEC SOIC, 8-lead TSSOP, 8-pad UDFN, 8-pad XDFN, and 8-ball VFBGA packages

Description

The Atmel® AT93C56B/66B provides 2,048/4,096 bits of Serial Electrically Erasable Programmable Read-Only Memory (EEPROM) organized as 128/256 words of 16 bits each (when the ORG pin is connected to $V_{\rm CC}$) and 256/512 words of 8 bits each (when the ORG pin is tied to ground). The device is optimized for use in many industrial and commercial applications where low-power and low-voltage operations are essential. The AT93C56B/66B is available in space-saving 8-lead JEDEC SOIC, 8-lead TSSOP, 8-pad UDFN, 8-pad XDFN, and 8-ball VFBGA packages.

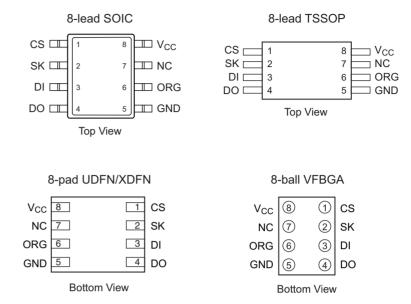
The AT93C56B/66B is enabled through the Chip Select pin (CS) and accessed via a 3-wire serial interface consisting of Data Input (DI), Data Output (DO), and Shift Clock (SK). Upon receiving a Read instruction at DI, the address is decoded, and the data is clocked out serially on the DO pin. The write cycle is completely self-timed, and no separate erase cycle is required before Write. The write cycle is only enabled when the part is in the Erase/Write Enable state. When CS is brought high following the initiation of a write cycle, the DO pin outputs the Ready/Busy status of the part.

The AT93C56B/66B operates from 1.7V to 5.5V.

1. Pin Configurations and Pinouts

Table 1-1. Pin Configurations

Pin Name	Function
CS	Chip Select
SK	Serial Data Clock
DI	Serial Data Input
DO	Serial Data Output
GND	Ground
V _{CC}	Power Supply
ORG	Internal Organization
NC	No Connect



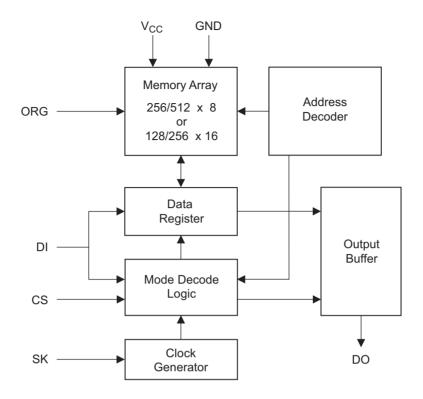
Note: Drawings are not to scale.

2. Absolute Maximum Ratings*

Operating Temperature55°C to +125°C
Storage Temperature65°C to +150°C
Voltage on any pin with respect to ground1.0V to +7.0V
Maximum Operating Voltage 6.25V
DC Output Current

*Notice: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

3. Block Diagram



Note: When the ORG pin is connected to V_{CC} , the x16 organization is selected. When it is connected to ground, the x8 organization is selected. If the ORG pin is left unconnected, and the application does not load the input beyond the capability of the internal $1M\Omega$ pull-up resistor, then the x16 organization is selected.



Memory Organization 4.

Pin Capacitance⁽¹⁾ 4.1

Applicable over recommended operating range from T_A = 25°C, f = 1.0MHz, V_{CC} = 5.0V (unless otherwise noted).

Symbol	Test Conditions	Max	Units	Conditions
C _{OUT}	Output Capacitance (DO)	5	pF	V _{OUT} = 0V
C _{IN}	Input Capacitance (CS, SK, DI)	5	pF	V _{IN} = 0V

Note: 1. This parameter is characterized, and is not 100% tested.

4.2 **DC Characteristics**

Applicable over recommended operating range from T_{AI} = -40°C to +85°C, V_{CC} = 1.7V to 5.5V (unless otherwise noted).

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit	
V _{CC1}	Supply Voltage		1.7		5.5	V	
V _{CC2}	Supply Voltage			2.5		5.5	V
V _{CC3}	Supply Voltage			4.5		5.5	V
,	Cumply Current	V - F 0V	Read at 1.0MHz		0.5	2.0	mA
I _{cc}	Supply Current	V _{CC} = 5.0V	Write at 1.0MHz		0.5	2.0	mA
I _{SB1}	Standby Current	V _{CC} = 1.7V	CS = 0V		0.4	1.0	μΑ
I _{SB2}	Standby Current	V _{CC} = 2.5V	CS = 0V		6.0	10.0	μΑ
I _{SB3}	Standby Current	V _{CC} = 5.0V	CS = 0V		10.0	15.0	μA
I _{IL}	Input Leakage	V _{IN} = 0V to V _{CC}	<u>'</u>		0.1	3.0	μΑ
I _{OL}	Output Leakage	V _{IN} = 0V to V _{CC}			0.1	3.0	μΑ
V _{IL1} ⁽¹⁾	Input Low Voltage	$2.5V \leq V_{CC} \leq 5.5V$		-0.6		0.8	V
V _{IH1} ⁽¹⁾	Input High Voltage	$2.5V \leq V_{CC} \leq 5.5V$		2.0		V _{CC} + 1	V
V _{IL2} ⁽¹⁾	Input Low Voltage	$1.7V \leq V_{CC} \leq 2.5V$		-0.6		V _{CC} x 0.3	V
V _{IH2} ⁽¹⁾	Input High Voltage	$1.7V \leq V_{CC} \leq 2.5V$		V _{CC} x 0.7		V _{CC} + 1	V
V _{OL1}	Output Low Voltage	$2.5V \leq V_{CC} \leq 5.5V$	I _{OL} = 2.1mA			0.4	V
V _{OH1}	Output High Voltage	$2.5 \text{V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{V}$	I _{OH} = -0.4mA	2.4			V
V _{OL2}	Output Low Voltage	$1.7V \le V_{CC} \le 2.5V$	I _{OL} = 0.15mA			0.2	V
V _{OH2}	Output High Voltage	$1.7 \text{V} \leq \text{V}_{\text{CC}} \leq 2.5 \text{V}$	I _{OH} = -100μA	V _{CC} - 0.2			V

Note: 1. V_{IL} min and V_{IH} max are reference only, and are not tested.

4.3 AC Characteristics

Applicable over recommended operating range from T_{AI} = -40°C to + 85°C, V_{CC} = as specified, CL = 1 TTL gate and 100pF (unless otherwise noted).

Symbol	Parameter	Test Condition	1	Min	Max	Units
		4.5V ≤ V _{CC} ≤ 5	$4.5V \leq V_{CC} \leq 5.5V$		2	MHz
f _{SK}	SK Clock Frequency	2.5V ≤ V _{CC} ≤ 5	$2.5V \le V_{CC} \le 5.5V$			MHz
		1.7V ≤ V _{CC} ≤ 5	.5V	0	250	kHz
4	CV High Time	$2.5V \le V_{CC} \le 5$.5V	250		ns
t _{SKH}	SK High Time	1.7V ≤ V _{CC} ≤ 5	.5V	1000		ns
+	SK Low Time	2.5V ≤ V _{CC} ≤ 5	.5V	250		ns
t _{SKL}	SK LOW TIME	1.7V ≤ V _{CC} ≤ 5	.5V	1000		ns
+	Minimum CS Low Time	$2.5V \le V_{CC} \le 5$.5V	250		ns
t _{cs}	Willimidiff C3 Low Time	1.7V ≤ V _{CC} ≤ 5	.5V	1000		ns
4	CS Setup Time	Relative to SK	$2.5 \text{V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{V}$	50		ns
t _{css}	C3 Setup Time	Relative to SK	$1.7V \le V_{CC} \le 5.5V$	200		ns
+	DI Catura Tima	Relative to SK	$2.5 \text{V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{V}$	100		ns
t _{DIS}	DI Setup Time	Relative to SR	$1.7V \le V_{CC} \le 5.5V$	400		ns
t _{CSH}	CS Hold Time	Relative to SK		0		ns
4	DI Hald Time	old Time Relative to SK	$2.5V \le V_{CC} \le 5.5V$	100		ns
t _{DIH}	DI Hold Time	Relative to SK	$1.7 \text{V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{V}$	400		ns
+	Output Delay to 1	AC Test	$2.5 \text{V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{V}$		250	ns
t _{PD1}	Output Delay to 1	AC Test	$1.7V \le V_{CC} \le 5.5V$		1000	ns
4	Output Delay to 0	AC Toot	$2.5 \text{V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{V}$		250	ns
t _{PD0}	Output Delay to 0	AC Test	$1.7V \le V_{CC} \le 5.5V$		1000	ns
4	CS to Status Valid	AC Test	$2.5 \text{V} \leq \text{V}_{\text{CC}} \leq 5.5 \text{V}$		250	ns
t _{SV}	CS to Status Valid	AC TEST	$1.7V \le V_{CC} \le 5.5V$		1000	ns
+	CS to DO in	AC Test	$2.5V \leq V_{CC} \leq 5.5V$		150	ns
t _{DF}	High-impedance	CS = V _{IL}	$1.7V \le V_{CC} \le 5.5V$		400	ns
t _{WP}	Write Cycle Time		$1.7V \le V_{CC} \le 5.5V$		5	ms
Endurance ⁽¹⁾	5.0V, 25°C			1,000	0,000	Write Cycles

Note: 1. This parameter is characterized, and is not 100% tested.



5. Functional Description

The AT93C56B/66B is accessed via a simple and versatile 3-wire serial communication interface. Device operation is controlled by seven instructions issued by the Host processor. A valid instruction starts with a rising edge of CS and consists of a Start bit (Logic 1), followed by the appropriate opcode, and the desired memory address location.

Table 5-1. AT93C56B/66B Instruction Set

			Addr	ess	Data		
Instruction	SB	Opcode	x8 ⁽¹⁾	x16 ⁽¹⁾	x8	x16	Comments
READ	1	10	$A_8 - A_0$	$A_7 - A_0$			Reads data stored in memory at specified address.
EWEN	1	00	11XXXXXXX	11XXXXXX			Write Enable must precede all programming modes.
ERASE	1	11	$A_8 - A_0$	$A_7 - A_0$			Erases memory location A _N – A ₀ .
WRITE	1	01	$A_8 - A_0$	$A_7 - A_0$	D ₇ – D ₀	D ₁₅ – D ₀	Writes memory location $A_N - A_0$.
ERAL	1	00	10XXXXXXX	10XXXXXX			Erases all memory locations. Valid only at V _{CC3} (Section 4.2, "DC Characteristics" on page 4).
WRAL	1	00	01XXXXXXX	01XXXXXX	D ₇ – D ₀	D ₁₅ – D ₀	Writes all memory locations. Valid only at V_{CC3} (Section 4.2) and Disable Register cleared.
EWDS	1	00	00XXXXXXX	00XXXXXX			Disables all programming instructions.

Note: 1. The Xs in the address field represent don't care values, and must be clocked.

READ: The READ instruction contains the address code for the memory location to be read. After the instruction and address are decoded, data from the selected memory location is available at the Serial Output pin, DO. Output data changes are synchronized with the rising edges of the Serial Clock pin, SK. It should be noted that a dummy bit (Logic 0) precedes the 8-bit or 16-bit data output string. The AT93C56B/66B supports sequential Read operations. The device will automatically increment the internal address pointer and clock out the next memory location as long as Chip Select (CS) is held high. In this case, the dummy bit (Logic 0) will not be clocked out between memory locations, thus allowing for a continuous stream of data to be read.

Erase/Write Enable (EWEN): To ensure data integrity, the part automatically goes into the Erase/Write Disable (EWDS) state when power is first applied. An Erase/Write Enable (EWEN) instruction must be executed first before any programming instructions can be carried out.

Note: Once in the EWEN state, programming remains enabled until an EWDS instruction is executed, or V_{CC} power is removed from the part.

ERASE: The ERASE instruction programs all bits in the specified memory location to the Logic 1 state. The self-timed erase cycle starts once the ERASE instruction and address are decoded. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of t_{CS} . A Logic 1 at the DO pin indicates that the selected memory location has been erased, and the part is ready for another instruction.

WRITE: The WRITE instruction contains the 8-bits or 16-bits of data to be written into the specified memory location. The self-timed programming cycle, t_{WP} , starts after the last bit of data is received at Serial Data Input pin DI. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of t_{CS} . A

Logic 0 at DO indicates that programming is still in progress. A Logic 1 indicates that the memory location at the specified address has been written with the data pattern contained in the instruction, and the part is ready for further instructions. A Ready/Busy status cannot be obtained if CS is brought high after the end of the self-timed programming cycle, t_{WP} .

Erase All (ERAL): The Erase All (ERAL) instruction programs every bit in the Memory Array to the Logic 1 state and is primarily used for testing purposes. The DO pin outputs the ready/busy status of the part if CS is brought high after being kept low for a minimum of t_{CS} . The ERAL instruction is valid only at V_{CC3} (Section 4.2, "DC Characteristics" on page 4).

Write All (WRAL): The Write All (WRAL) instruction programs all memory locations with the data patterns specified in the instruction. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of t_{CS} . The WRAL instruction is valid only at V_{CC3} (Section 4.2).

Erase/Write Disable (EWDS): To protect against accidental data disturbance, the Erase/Write Disable (EWDS) instruction disables all programming modes and should be executed after all programming operations. The operation of the Read instruction is independent of both the EWEN and EWDS instructions and can be executed at any time.



6. Timing Diagrams

Figure 6-1. Synchronous Data Timing

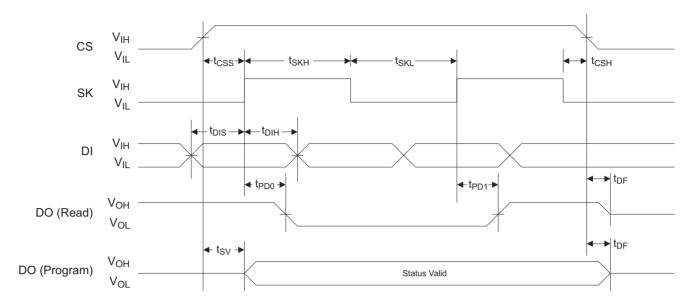


Table 6-1. Organization Key for Timing Diagrams

	AT93C5	66B (2K)	AT93C6	66B (4K)
I/O	x8	x16	x8	x16
A _N	A ₈ ⁽¹⁾	A ₇ ⁽²⁾	A ₈	A ₇
D _N	D ₇	D ₁₅	D ₇	D ₁₅

Notes: 1. A_8 is a don't-care value, but the extra clock is required.

2. A₇ is a don't-care value, but the extra clock is required.

Figure 6-2. READ Timing

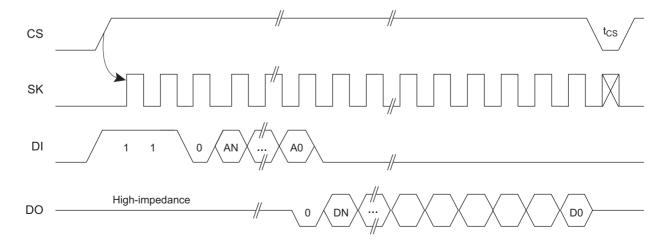


Figure 6-3. EWEN Timing

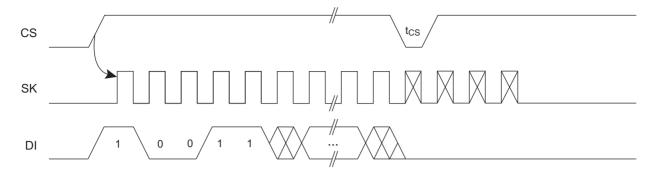


Figure 6-4. ERASE Timing

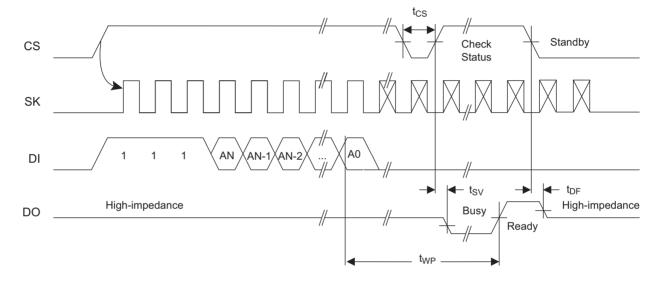


Figure 6-5. WRITE Timing

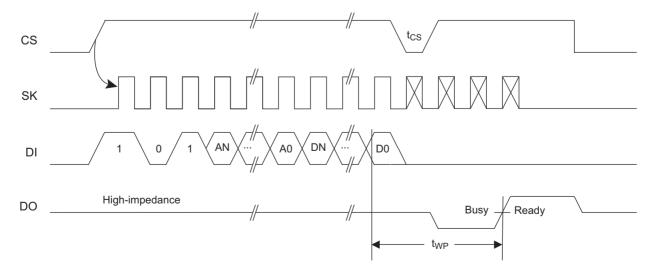
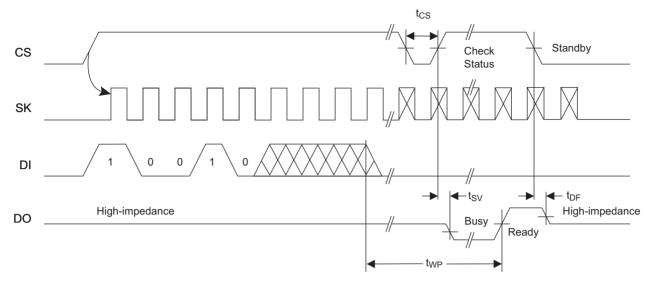


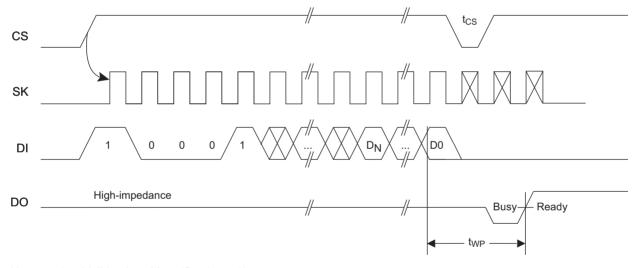


Figure 6-6. ERAL Timing⁽¹⁾



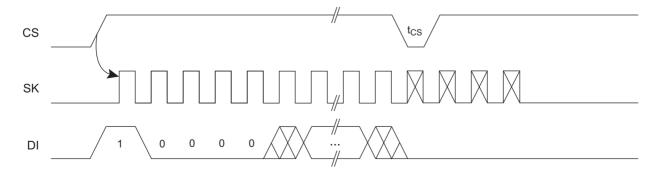
Note: 1. Valid only at V_{CC3} (Section 4.2).

Figure 6-7. WRAL Timing⁽¹⁾

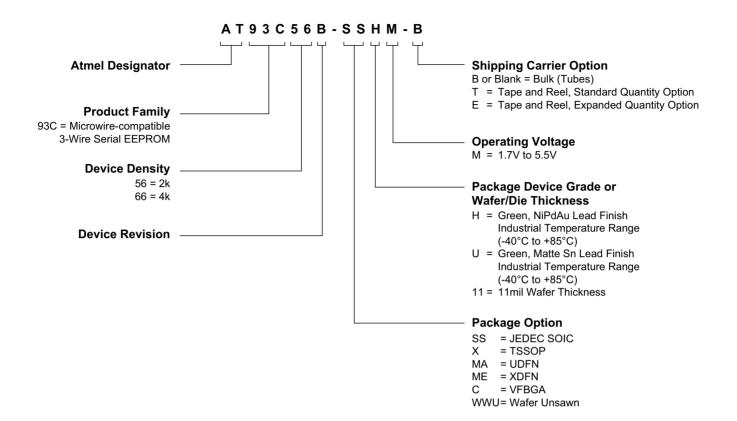


Note: 1. Valid only at V_{CC3} (Section 4.2).

Figure 6-8. EWDS Timing



7. Ordering Code Detail





8. Ordering Information

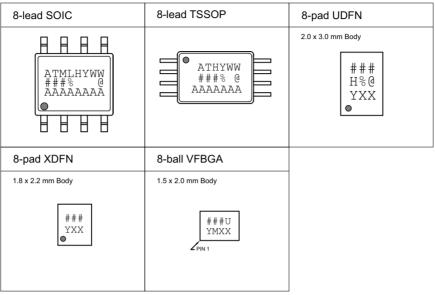
			Delivery Information		Operation
Atmel Ordering Code	Lead Finish	Package	Form	Quantity	Range
AT93C56B-SSHM-B	-В		Bulk (Tubes)	100 per Tube	
AT93C56B-SSHM-T		8S1	Tape and Reel	4,000 per Reel	
AT93C56B-XHM-B		ov.	Bulk (Tubes)	100 per Tube	
AT93C56B-XHM-T	NiPdAu (Lead-free/Halogen-free)	8X	Tape and Reel	5,000 per Reel	
AT93C56B-MAHM-T		OMAG	Tape and Reel	5,000 per Reel	Industrial Temperature
AT93C56B-MAHM-E		8MA2	Tape and Reel	15,000 per Reel	(-40°C to 85°C)
AT93C56B-MEHM-T		8ME1	Tape and Reel	5,000 per Reel	
AT93C56B-CUM-T	SnAgCu (Lead-free/Halogen-free)	8U3-1	Tape and Reel	5,000 per Reel	
AT93C56B-WWU11M ⁽¹⁾	N/A	Wafer Sale	No	Note 1	
AT93C66B-SSHM-B			Bulk (Tubes)	100 per Tube	
AT93C66B-SSHM-T		8S1	Tape and Reel	4,000 per Reel	
AT93C66B-XHM-B			Bulk (Tubes)	100 per Tube	
AT93C66B-XHM-T	NiPdAu (Lead-free/Halogen-free)	8X	Tape and Reel	5,000 per Reel	
AT93C66B-MAHM-T		00440	Tape and Reel	5,000 per Reel	Industrial Temperature
AT93C66B-MAHM-E		8MA2	Tape and Reel	15,000 per Reel	(-40°C to 85°C)
AT93C66B-MEHM-T		8ME1	Tape and Reel	5,000 per Reel	
AT93C66B-CUM-T	SnAgCu (Lead-free/Halogen-free)	8U3-1	Tape and Reel	5,000 per Reel	
AT93C66B-WWU11M ⁽¹⁾	N/A	Wafer Sale	No	ote 1	

Note: 1. For wafer sales, please contact Atmel sales.

	Package Type
8S1	8-lead, 0.150" wide, Plastic Gull Wing, Small Outline (JEDEC SOIC)
8X	8-lead, 0.170" wide, Thin Shrink Small Outline (TSSOP)
8MA2	8-pad, 2.00mm x 3.00mm body, 0.50mm pitch, Ultra Thin Dual No Lead (UDFN)
8ME1	8-pad, 1.80mm x 2.20mm body, Extra Thin Dual No Lead (XDFN)
8U3-1	8-ball, 1.50mm x 2.00mm body, 0.50mm pitch, Small Die Ball Grid Array (VFBGA)

9. Part Markings

AT93C56B and AT93C66B: Package Marking Information



Note 1: designates pin 1

Note 2: Package drawings are not to scale

Catalog Number Truncation								
AT93C56B				Truncation Code ###: 56B				
AT93C66B Truncation Code ###: 66B								
Date Code	es				Voltage	s		
Y = Year		M = Month		WW = Work Week of Assembly	% :	= Minimum Voltage		
3: 2013	7: 2017	A: January		02: Week 2	M:	1.7V min		
4: 2014	8: 2018	B: Februar	y	04: Week 4				
5: 2015	9: 2019							
6: 2016	0: 2020	L: Decemb	er	52: Week 52				
Country o	f Assembly	•	Lot Nu	umber Grade/Lead Finish Mat		_ead Finish Material		
@ = Country of Assembly AAA		AAA	A = Atmel Wafer Lot Number	U: H:	Industrial/Matte Tin/SnAgCu Industrial/NiPdAu			
Trace Code			Atmel T	runcation				
XX = Trace Code (Atmel Lot Numbers Correspond to Code) Example: AA, AB YZ, ZZ			AT: ATM: ATML:	Atmel Atmel Atmel				

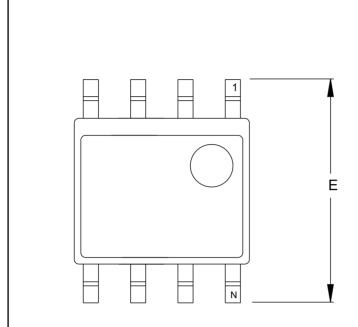
3/22/13

Atmel	TITLE	DRAWING NO.	REV.
Package Mark Contact: DL-CSO-Assy_eng@atmel.com	93C56-66BSM, AT93C56B and AT93C66B Package Marking Information	93C56-66BSM	В

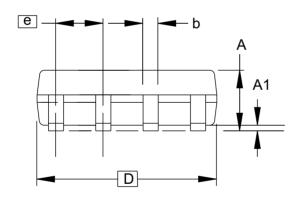


10. Packaging Information

10.1 8S1 — 8-lead JEDEC SOIC



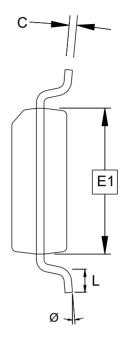
TOP VIEW



SIDE VIEW

Notes: This drawing is for general information only.

Refer to JEDEC Drawing MS-012, Variation AA for proper dimensions, tolerances, datums, etc.



END VIEW

COMMON DIMENSIONS (Unit of Measure = mm)

MIN	NOM	MAX	NOTE
1.35	_	1.75	
0.10	_	0.25	
0.31	_	0.51	
0.17	_	0.25	
4.80	_	5.05	
3.81	_	3.99	
5.79	_	6.20	
	1.27 BSC	,	
0.40	_	1.27	
0°	_	8°	
	1.35 0.10 0.31 0.17 4.80 3.81 5.79	1.35	1.35 - 1.75 0.10 - 0.25 0.31 - 0.51 0.17 - 0.25 4.80 - 5.05 3.81 - 3.99 5.79 - 6.20 1.27 BSC 0.40 - 1.27

6/22/11

Atmel

Package Drawing Contact: packagedrawings@atmel.com

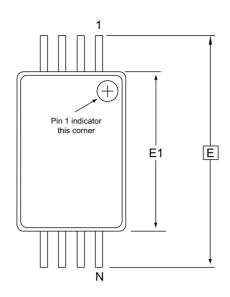
TITLE 851 8 load (0.150" W

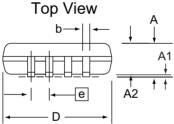
8S1, 8-lead (0.150" Wide Body), Plastic Gull Wing Small Outline (JEDEC SOIC)

GPC SWB

DRAWING NO. REV. 8S1 G

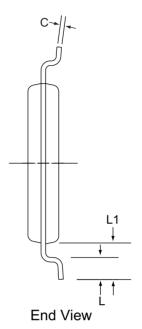
10.2 8X — 8-lead TSSOP





Side View

- Notes: 1. This drawing is for general information only. Refer to JEDEC Drawing MO-153, Variation AA, for proper dimensions, tolerances, datums, etc.
 - 2. Dimension D does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15mm (0.006in) per side.
 - 3. Dimension E1 does not include inter-lead Flash or protrusions. Inter-lead Flash and protrusions shall not exceed 0.25mm (0.010in) per side.
 - 4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07mm.
 - 5. Dimension D and E1 to be determined at Datum Plane H.



COMMON DIMENSIONS (Unit of Measure = mm)

	`		,	
SYMBOL	MIN	NOM	MAX	NOTE
Α	-	-	1.20	
A1	0.05	-	0.15	
A2	0.80	1.00	1.05	
D	2.90	3.00	3.10	2, 5
E	6.40 BSC			
E1	4.30	4.40	4.50	3, 5
b	0.19	0.25	0.30	4
е	0.65 BSC			
L	0.45	0.60	0.75	
L1	1.00 REF			
С	0.09	-	0.20	

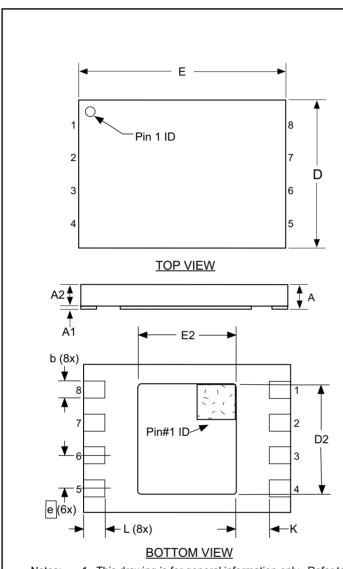
2/27/14

Atmel

Package Drawing Contact: packagedrawings@atmel.com TITLE 8X, 8-lead 4.4mm Body, Plastic Thin Shrink Small Outline Package (TSSOP) GPC DRAWING NO. REV. **TNR** 8X Ε



10.3 8MA2 — 8-pad UDFN



← C

SIDE VIEW

COMMON DIMENSIONS (Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
Α	0.50	0.55	0.60	
A1	0.0	0.02	0.05	
A2	-	-	0.55	
D	1.90	2.00	2.10	
D2	1.40	1.50	1.60	
E	2.90	3.00	3.10	
E2	1.20	1.30	1.40	
b	0.18	0.25	0.30	3
С	1.52 REF			
L	0.30	0.35	0.40	
е	0.50 BSC			
K	0.20	-	-	

11/26/14

Notes:

- This drawing is for general information only. Refer to Drawing MO-229, for proper dimensions, tolerances, datums, etc.
- 2. The Pin #1 ID is a laser-marked feature on Top View.
- Dimensions b applies to metallized terminal and is measured between 0.15 mm and 0.30 mm from the terminal tip. If the terminal has the optional radius on the other end of the terminal, the dimension should not be measured in that radius area.
- 4. The Pin #1 ID on the Bottom View is an orientation feature on the thermal pad.

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Package Drawing Contact: packagedrawings@atmel.com

TITLE

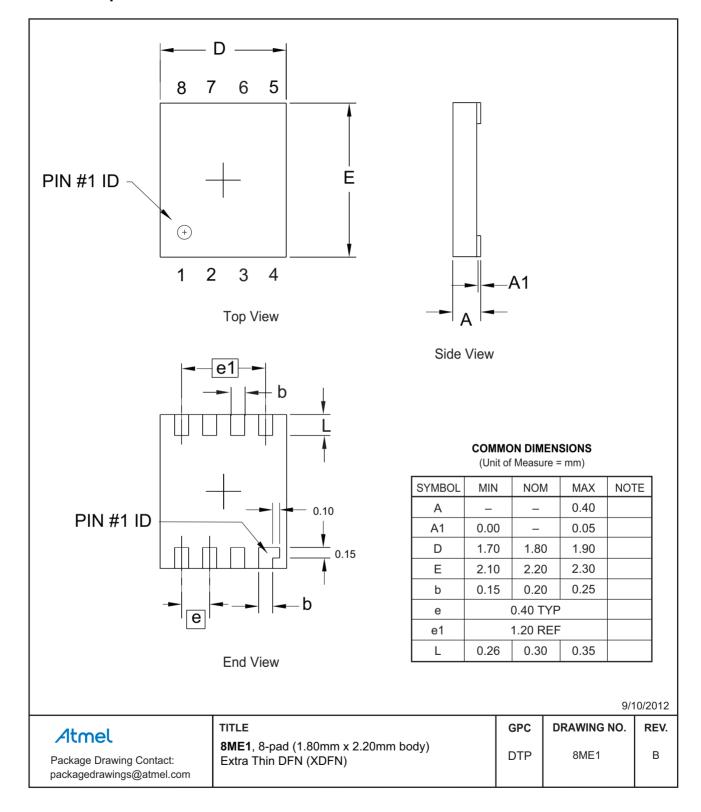
8MA2, 8-pad 2 x 3 x 0.6mm Body, Thermally Enhanced Plastic Ultra Thin Dual Flat No-Lead Package (UDFN)

GPC YNZ

DRAWING NO. 8MA2

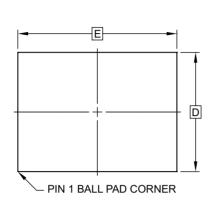
o. REV.

10.4 8ME1 — 8-pad XDFN

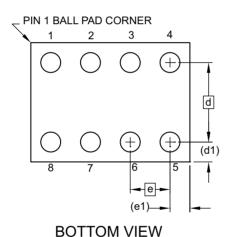




10.5 8U3-1 — 8-ball VFBGA



TOP VIEW



Notes:

- 1. This drawing is for general information only.
- 2. Dimension 'b' is measured at maximum solder ball diameter.

8 SOLDER BALLS

3. Solder ball composition shall be 95.5Sn-4.0Ag-.5Cu.

A2 —— A1

SIDE VIEW

COMMON DIMENSIONS (Unit of Measure - mm)

SYMBOL	MIN	NOM	MAX	NOTE
А	0.73	0.79	0.85	
A1	0.09	0.14	0.19	
A2	0.40	0.45	0.50	
b	0.20	0.25	0.30	2
D	1.50 BSC			
E	2.0 BSC			
е	0.50 BSC			
e1	0.25 REF			
d	1.00 BSC			
d1	0.25 REF			

6/11/13 REV.

Atmel

Package Drawing Contact: packagedrawings@atmel.com

TITLE

8U3-1, 8-ball, 1.50mm x 2.00mm body, 0.50mm pitch, Very Thin, Fine-Pitch Ball Grid Array Package (VFBGA)

GPC DRAWING NO.
GXU 8U3-1

F

11. Revision History

Rev. No.	Date	Comments
8735C	01/2015	Add the UDFN extended quantity option and update package outline drawings. Update the 8MA2 package drawing.
8735B	04/2013	Correct Synchronous Data Timing figure and remove note. Update TSSOP package option from 8A2 to 8X. Update UDFN package option from 8Y6 to 8MA2. Update template and Atmel logos.
8735A	01/2011	Initial document release.













Atmel Corporation

1600 Technology Drive, San Jose, CA 95110 USA

T: (+1)(408) 441.0311

F: (+1)(408) 436.4200

www.atmel.com

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